



Features

- ESD/Surge protect for 4 high-speed I/O channels
- Provide ESD protection for each line to
IEC 61000-4-2 (ESD) ±27kV (air), ±25kV (contact)
IEC 61000-4-4 (EFT) 50A (5/50ns)
IEC 61000-4-5 (Lightning) 12A (8/20μs)
- For operating voltage of 3.3V and below
- Low capacitance : 0.5pF typical
- Fast turn-on and low clamping voltage
- Array of ESD rated diodes with internal equivalent TVS (Transient Voltage Suppression) diode
- Solid-state silicon-avalanche and active circuit triggering technology
- **Green part**

Applications

- **High Definition Multi-Media Interface (HDMI)**
1.3 & 1.4 and 2.0 version
- **DisplayPort interface**
- **SATA and eSATA interface**
- **USB3.0**
- **V-By-One**
- **LVDS interfaces**
- Ethernet port: 10/100/1000 Mb/s
- Desktop and Notebooks PCs

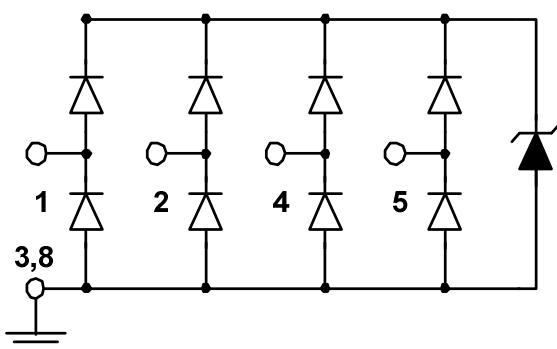
Description

AZ1243-04F is a high performance design which includes ESD rated diode arrays to protect high speed data interfaces. The AZ1243-04F has been specifically designed to protect sensitive components, which are connected to data and transmission lines, from over-voltage caused by Electrostatic Discharging (ESD), Lightning, and Cable Discharge Event (CDE).

AZ1243-04F is a unique design which includes ESD rated, ultra low capacitance steering diodes and a unique design of clamping cell which is an equivalent TVS diode in a single package. During transient conditions, the steering diodes direct the transient to either the internal ESD line or to ground line. The internal unique design of clamping cell prevents over-voltage on the internal ESD line and on the I/O line, which is protecting any downstream components.

AZ1243-04F may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 ($\pm 15\text{kV}$ air, $\pm 8\text{kV}$ contact discharge).

Circuit Diagram



Pin Configuration

Line-1	1	10	NC
Line-2	2	9	NC
GND	3	8	GND
Line-3	4	7	NC
Line-4	5	6	NC

DFN2510P10E (Top View)



SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise specified)			
PARAMETER	SYMBOL	RATING	UNITS
Peak Pulse Current ($t_p = 8/20\mu\text{s}$)	I_{PP} (Note 1)	12	A
Operating Voltage (I/O pin-GND)	V_{DC}	3.6	V
ESD per IEC 61000-4-2 (Air)	V_{ESD-1}	27	kV
ESD per IEC 61000-4-2 (Contact)	V_{ESD-2}	25	
Lead Soldering Temperature	T_{SOL}	260 (10 sec.)	$^\circ\text{C}$
Operating Temperature	T_{OP}	-55 to +125	$^\circ\text{C}$
Storage Temperature	T_{STO}	-55 to +150	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS						
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Reverse Stand-Off Voltage	V_{RWM}	$V_{Pin-1,-2,-4,-5} = 3.3\text{V}$, $V_{Pin-3,-8} = 0\text{V}$, $T = 25^\circ\text{C}$.			3.3	V
Channel Leakage Current	$I_{CH-Leak}$	$T = 25^\circ\text{C}$.			1	μA
Reverse Breakdown Voltage	V_{BV}	$I_{BV} = 1\text{mA}$, $T = 25^\circ\text{C}$, Pin-1,-2,-4,-5 to pin-3,-8.	4.5		7.5	V
Forward Voltage	V_F	$I_F = 15\text{mA}$, $T = 25^\circ\text{C}$, pin-3,-8 to pin-1,-2,-4,-5.	0.6		1.2	V
Lightning Clamping Voltage (Note 1)	$V_{CL-surge}$	$I_{PP} = 5\text{A}$, $t_p = 8/20\mu\text{s}$, $T = 25^\circ\text{C}$, I/O pin to GND.		5.5		V
ESD Clamping Voltage (Note 2)	V_{clamp}	IEC 61000-4-2 +8kV ($I_{TLP} = 16\text{A}$), Contact mode, $T = 25^\circ\text{C}$, I/O pin to GND.		8.5		V
ESD Dynamic Turn on Resistance	$R_{dynamic}$	IEC 61000-4-2 0 ~ +8kV, $T = 25^\circ\text{C}$, Contact mode, I/O pin to GND.		0.22		Ω
Channel Input Capacitance	C_{IN}	$V_{Pin-3,-8} = 0\text{V}$, $V_{IN} = 1.65\text{V}$, $f = 1\text{MHz}$, $T = 25^\circ\text{C}$, any I/O pin to GND.		0.5	0.65	pF
Channel to Channel Input Capacitance	C_{CROSS}	$V_{Pin-3,-8} = 0\text{V}$, $V_{IN} = 1.65\text{V}$, $f = 1\text{MHz}$, $T = 25^\circ\text{C}$, between I/O pins.		0.06	0.1	pF

Note 1: The Peak Pulse Current measured conditions: $t_p = 8/20\mu\text{s}$, 2ohm source impedance.

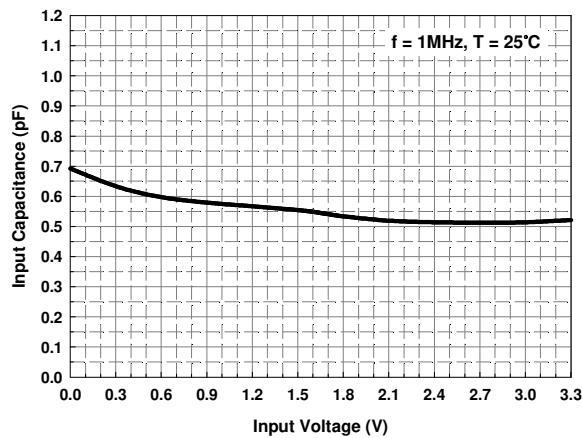
Note 2: ESD Clamping Voltage was measured by Transmission Line Pulsing (TLP) System.

TLP conditions: $Z_0 = 50\Omega$, $t_p = 100\text{ns}$, $t_r = 1\text{ns}$.

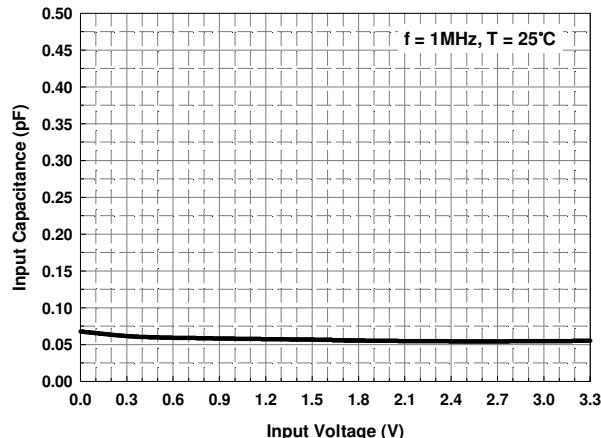


Typical Characteristics

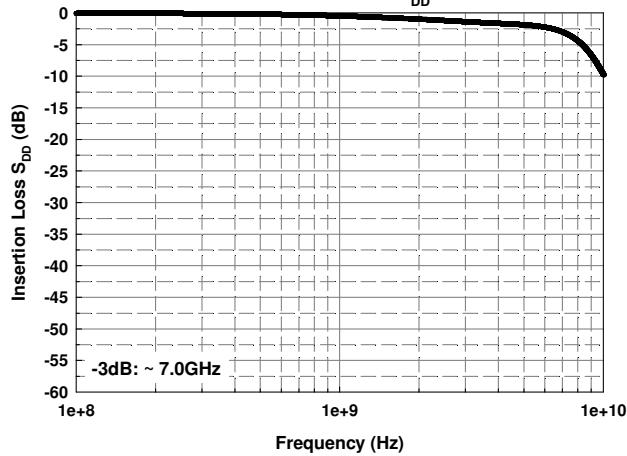
Typical Variation C_{IN} vs. V_{IN}



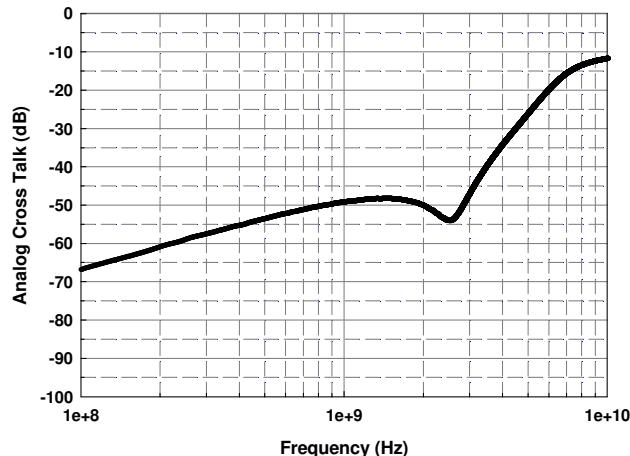
Typical Variation $C_{IO-to-IO}$ vs. V_{IN}



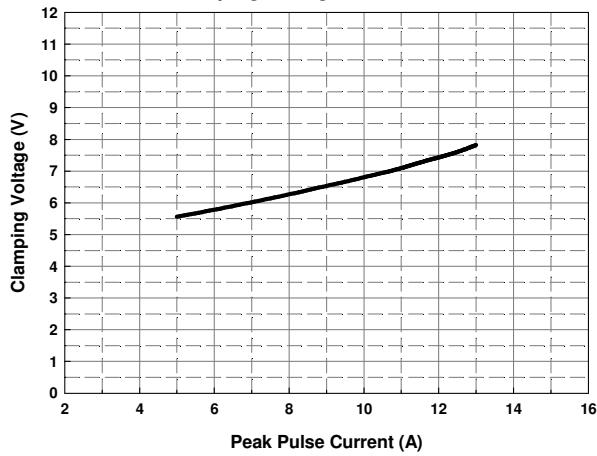
Insertion Loss S_{DD}



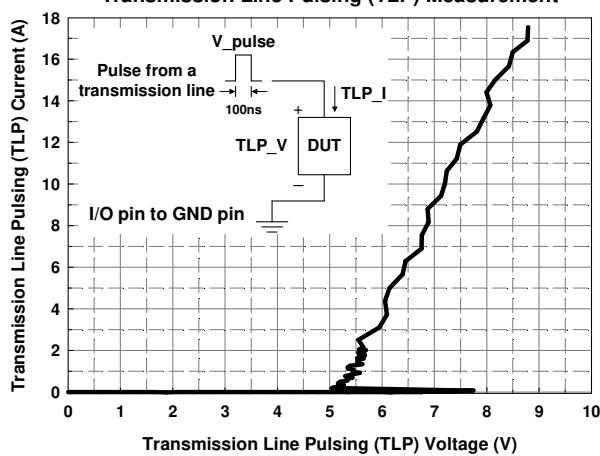
Analog Cross Talk



Reverse Clamping Voltage vs. Peak Pulse Current

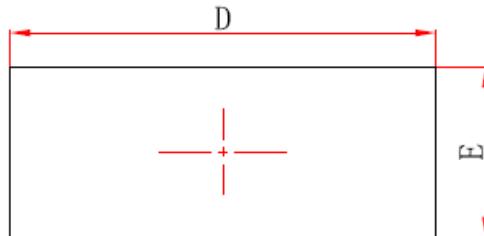


Transmission Line Pulsing (TLP) Measurement

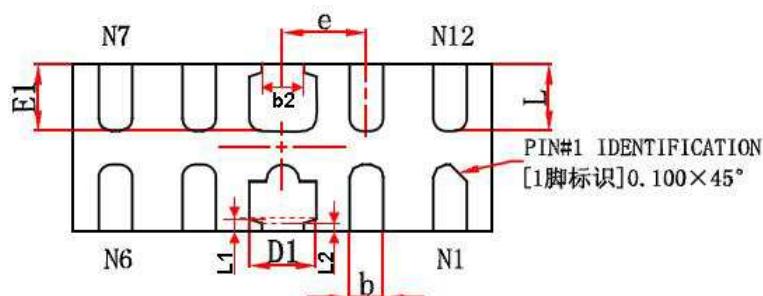




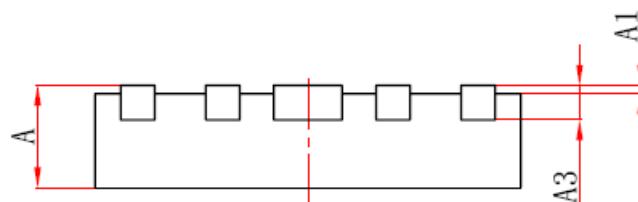
PACKAGE OUTLINE (DFN2510P10E)



TOP VIEW (unit in mm)



BOTTOM VIEW (unit in mm)

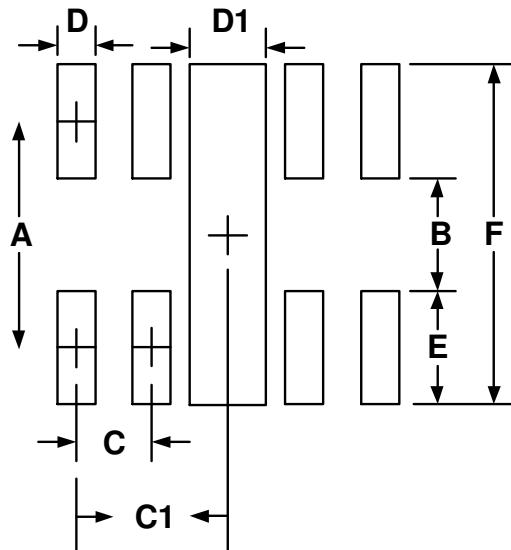


SIDE VIEW (unit in mm)

Symbol	Millimeters		Inches	
	min	max	min	max
A	0.40	0.55	0.016	0.022
A1	0.00	0.05	0.000	0.002
A3	0.152REF.		0.006 BSC	
D	2.45	2.55	0.096	0.100
E	0.95	1.05	0.037	0.041
D1	0.35	0.45	0.014	0.018
E1	0.35	0.45	0.014	0.018
b	0.15	0.25	0.006	0.010
e	0.5 BSC		0.019 BSC	
L1	0.075 REF		0.0029 REF	
L2	0.05 REF		0.0019 REF	
b2	0.20	0.30	0.0079	0.012
L	0.35	0.45	0.014	0.018



LAND LAYOUT



Dimensions		
Index	Millimeter	Inches
A	0.875	0.034
B	0.20	0.008
C	0.50	0.02
C1	1.00	0.039
D	0.25	0.01
D1	0.4	0.016
E	0.675	0.027
F	1.55	0.061

Notes:

This LAND LAYOUT is for reference purposes only. Please consult your manufacturing partners to ensure your company's PCB design guidelines are met.

MARKING CODE



243 = Device Code

X = Date Code

Y= Control Code

Part Number	Marking Code
AZ1243-04F.R7G (Green Part)	243XY

Note. Green means Pb-free, RoHS, and Halogen free compliant.

Ordering Information

PN#	Material	Type	Reel size	MOQ	MOQ/internal box	MOQ/carton
AZ1243-04F.R7G	Green	T/R	7 inch	3,000/reel	4 reels = 12,000/box	6 boxes = 72,000/carton



Revision History

Revision	Modification Description
Revision 2017/05/17	Formal Release.